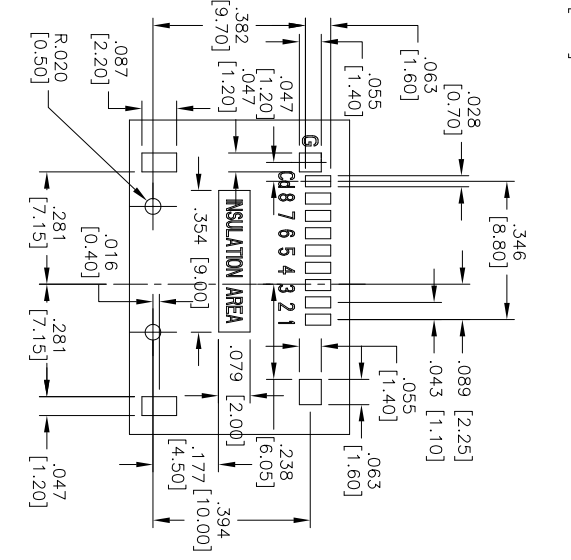
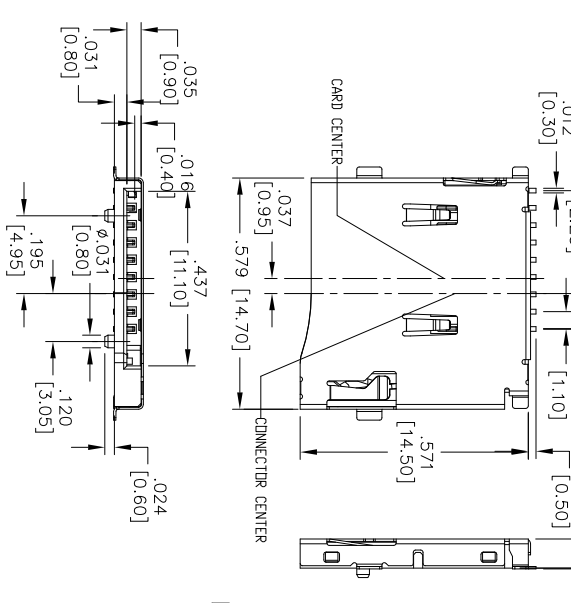
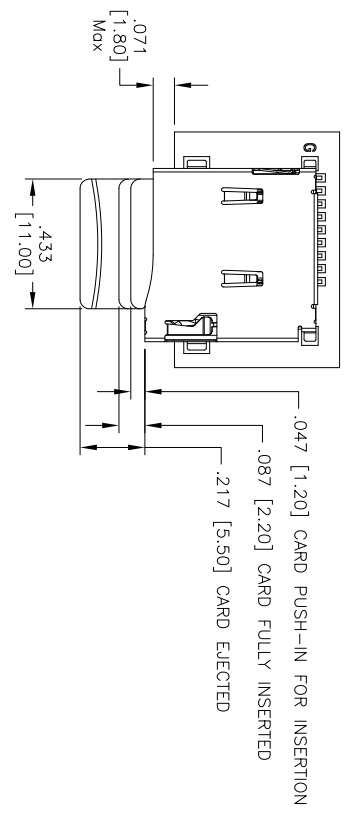
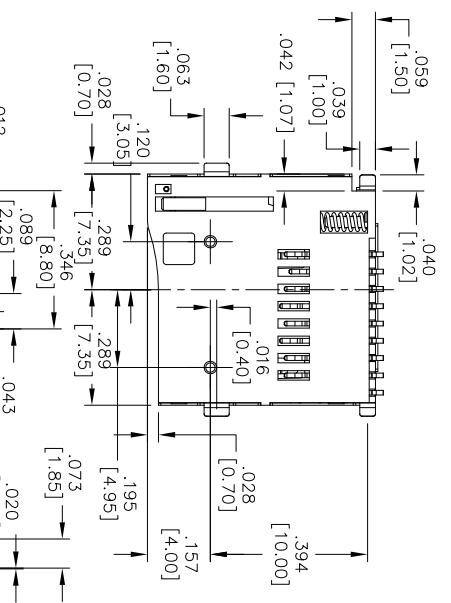


Rev	AWO #	Description	Date	Appr
-		RELEASED	1/07/10	



PIN NUMBER	PIN ASSIGNMENT	PIN NUMBER	PIN ASSIGNMENT
1	DATA	6	VSS
2	CD/DAT3	7	DAT0
3	CMD	8	DAT1
4	VDD	CA	CARD DETECTION
5	CLK	G	GROUND

ADAM TECH

909 Rahway Avenue, Union, NJ 07083
 Phone: 908-687-5000 Fax: 908-687-5710

MICRO SD SOCKET, PUSH-PUSH TYPE

SIZE	PART NO.	REV.
X	MCSP-08-C-SG	-
REF:	S00009T	SCALE: NTS
		SHEET 1 OF 1

RECOMMENDED PCB LAYOUT

UNLESS OTHERWISE SPECIFIED
 ALL DIMENSIONS ARE INCHES [MM]
 TOLERANCES: EXCEPT AS NOTED
 INCHES HOLES
 .X ± .10 Ø.X ± .10
 .XX ± .020 Ø.XX ± .015
 .XXX ± .015 Ø.XXX ± .010

APPROVALS	DATE
DRAWN	DY
CHECKED	
APPROVED	

1/07/10



SPECIFICATIONS:
 Material: Insulator: LCP, glass reinforced, rated UL 94V-0
 Contact: Phosphor Bronze
 Plating: Gold over Nickel underplate on contact area, Tin over Copper underplate on SMT tails
 Electrical: Current rating: 0.5 Amps max
 Contact resistance: 30 mohms max
 Insulation resistance: 1000 Mohms min @ 500V DC
 Dielectric withstanding voltage: 500 VAC for 1 minute
 Temperature Rating: Operating temperature: -25°C to +85°C
 Environmental: Lead free, RoHS compliant.
 Recommended soldering temp: 260°C for 5 sec.